EXHIBIT H

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AOS'S PRELIMINARY CLAIM CONSTRUCTION PURSUANT TO PATENT LOCAL RULE 4-2 (C 07-2638 JSW)

Filed 03/13/2008

In accordance with Patent L.R. 4-2, Plaintiffs and Counterdefendants Alpha & Omega Semiconductor, LTD and Alpha & Omega Semiconductor, Inc. ("AOS") submit this preliminary claim construction statement. Discovery in this case is still in the early stages and AOS's discovery and investigation in connection with this lawsuit are continuing. AOS believes that further extrinsic evidence, including expert or fact testimony, may assist in explaining the asserted claims and terms contained therein in view of claim interpretations advanced by Fairchild Semiconductor Corporation ("Fairchild"), the technical nature of the subject matter, the large number of patents and claims asserted, or a combination of these reasons.

Accordingly, AOS's preliminary claim construction, attached as Exhibit A, is given without prejudice to AOS's right to amend or supplement its disclosure after considering information obtained or reviewed through further discovery or investigation, or through the meet and confer process as outlined in the Patent Local Rules. Further, the consolidated list of proposed claim terms currently includes 37 terms, including 26 proposed by Fairchild. This greatly exceeds the ten-term limit imposed by the court's Standing Order for Patent Cases. AOS thus reserves the right to amend or supplement its disclosure as the list is reduced to ten terms. 1

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Dated: January 9, 2008

MORGAN, LEWIS & BOCKIUS LLP

Andrew J. Wu

Attorneys for Plaintiffs and Counterdefendants ALPHA & OMEGA SEMICONDUCTOR, LTD. AND ALPHA & OMEGA SEMICONDUCTOR, INC.

¹ The parties may seek leave of the court to construe more than ten terms.

Exhibit A AOS's Preliminary Claim Construction Pursuant to L.R. 4-2

Term	Preliminary Construction
1. gate runners ('567, claim 7)	conductive gate stripes that divide the source contact area into several sub-contact areas; the stripes need not be contiguous
2. determining a total number of lead wires ('567, claim 7)	selecting the total number of lead wires to be connected to the source contact area
3. MOSFET power device('567, claim 7)	a semiconductor device used for power management, which is built using metal oxide semiconductor field- effect transistor (MOSFET) technology.
4. configuring said gate runners ('567, claim 7)	selecting a placement of gate runners on the source contact area and forming the gate runners according to that placement
5. several sub-contact areas ('567, claim 7)	two or more subdivisions of the source contact area
6. set of area proportional ratios ('567, claim 7)	the ratios of the areas of the sub-contact areas
7. several ('567, claim 7)	more than one
8. configuring said gate runners for	the placement of gate runners divides the source contact
dividing said source contact area	area into sub-contact areas, and a set of area proportional
into several sub-contact areas with a	ratios are defined by the ratios of the approximate areas
set of area proportional ratios ('567, claim 7)	of the sub-contact areas
9. disposing several of said lead	connecting two or more lead wires to each sub-contact
wires in each of said sub-contact	area so that the ratio of lead wires to area is the same for
areas according to said set of area	each of the sub contact areas
proportional ratios ('567, claim 7)	
10. compensating a portion of said	implanting into the body region material having
body region by implanting material of said second conductivity type in said body region ('776, claims 1, 13, 25)	conductivity type opposite the conductivity type of the body region
11. proximal to said source region ('776, claim 1)	near the source region
12. adjacent to said source region ('776, claims 13, 25)	near the source region
13. so as to reduce the impurity concentration of said first conductivity type in said portion of said body region ('776, claim 1)	to create a net reduction in impurity charge in the portion
14. substantially reduced so as to decrease the gate threshold voltage of said trench gate	the impurity charge is reduced by a sizeable amount.
substantially reduced so as to	n e

Exhibit A AOS's Preliminary Claim Construction Pursuant to L.R. 4-2

decrease the gate threshold voltage	
of said gate	7
(*776 claims 13, 25)	
('776, claims 13, 25) 15. spaced from said diffusion	not touching the boundary between the body region and
boundary ('776, claims 1, 13, 25)	the substrate
16. applying a polysilicon mask for etching said polysilicon layer to define a plurality of polysilicon gates ('630, claim 1)	the meaning of this phrase is clear and unambiguous to a person of skill in the art, and thus it need not be construed by the court
17. overlying insulation layer ('630, claim 1)	a layer comprising an insulating material that is formed above the other layers
18. self-aligned ('630, claim 1)	the implant is performed without any additional mask applied to the region
19. top portion of said substrate ('630, claim 3)	a portion from the top of the substrate, which does not extend to the bottom of the source region
for etching said active layer ('630, claim 1)	for etching said oxide layer (typographical error in claim)
20. a pair of doped source junctions having dopants of the first conductivity type, and positioned on opposite sides of the trench	Fairchild no longer proposes to construe this term.
a pair of doped source junctions, positioned on opposite sides of the trench and extending along the length of the trench, the source junctions having the first conductivity type	
a pair of doped source regions formed on opposite sides of the trench	
('481, claims 1, 6, 15)	
21. a doped well formed into the substrate to a depth that is less than the predetermined depth of the trench	the maximum depth of the doped well is less than the maximum depth of the trench
a doped well formed into the substrate to a second depth that is	

Exhibit A AOS's Preliminary Claim Construction Pursuant to L.R. 4-2

less than said first depth of the trench	
a doped well in the substrate to a second depth that is less than said first depth of the plurality of trenches	
a well between adjacent trenches to a second depth that is shallower than the first depth	
a plurality of doped wells respectively to a second depth that is less than said first depth of the plurality of trenches	
('481, claim 1; '406, claim 1; '195, claim 1; '111, claim 29)	
22. said heavy body extending into said doped well to a depth that is less than said depth of said doped well ('481, claim 1)	Fairchild no longer proposes to construe this term.
23. the deepest portion of said heavy body extending less deeply into said semiconductor substrate than said predetermined depth of said trenches	Fairchild no longer proposes to construe this term.
the doped heavy body extending into the doped well to a second depth that is less than the first depth	
('481, claims 6, 15)	
24. wherein the heavy body forms an abrupt junction with the well	the doping concentration gradient at the junction between the heavy body and the well is sufficiently high that the breakdown voltage at the p-n junction between the well
wherein the doped heavy body forms an abrupt junction with the well	and the substrate cannot be reduced any further by increasing the doping concentration gradient
('481, claims 1, 6, 15; '406, claims 1, 4, 5, 13; '195, claims 1, 21, 22)	
25. depth of the junction, relative to the depth of the well, is adjusted so	selecting by repeated experiments or by computer simulation the relative depths of the well and the junction

Exhibit A AOS's Preliminary Claim Construction Pursuant to L.R. 4-2

that a transistor breakdown	so that initiation of breakdown in the device is moved
initiation point is spaced away from	
the trench in the semiconductor	toward the center of the body region between adjacent trenches
1	trenenes
when voltage is applied to the	
transistor	
a location of the abrupt junction	
relative to the depth of the well is	
adjusted so that a transistor	€
breakdown initiation point is spaced	
away from the trench in the	
semiconductor, when voltage is	
applied to the transistor	
applied to the transistor	
1 - 41 - C41 - 1 1 - 1 1 - 4 4 -	
depth of the heavy body relative to	
a depth of the well is adjusted so	
that breakdown of the transistor	
originates in the semiconductor in a	
region spaced away from the	
trenches when voltage is applied to	
the transistor	
depth of the heavy body junction	
relative to a maximum depth of the	
well, is adjusted so that a peak	0
electric field in the substrate is	
spaced away from the trench when	
voltage is applied to the transistor	
('481, claims 1, 6, 15; '406, claims	
1, 13)	
26. patterning ('497, claims 1, 7)	Fairchild no longer proposes to construe this term.
27. wherein said dosage of said	the dosage of the second dopant during implantation is
second dopant has a doping	greater than the dosage of the third dopant during
concentration that is greater than	implantation
said dosage of said third dopant	The state of the s
('497, claim 1)	
28. double implant process ('195,	an implant is determined by dopant, dosage, and energy
다 10~10, 100, 100, 100 HE	
claims 8, 9)	level; a double implant involves two implants, i.e., a first
	implant and a second implant, wherein at least one of
2	dopant, dosage, or energy level of the second implant is
	different from that of the first implant
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29. plurality of doped wells ('111,	Fairchild no longer proposes to construe this term.

Exhibit A AOS's Preliminary Claim Construction Pursuant to L.R. 4-2

claim 29)	
30. plurality of doped wells in the plurality of epitaxial mesas ('111, claim 29)	two or more doped wells are formed, each doped well must be formed in a region between two trenches
31. resulting in avalanche current that is substantially uniformly distributed ('111, claim 29)	the avalanche current at breakdown initiation is roughly equally distributed across the entire device
32. adjusting a dopant profile of the plurality of heavy body regions so that peak electric field is moved away from a nearby trench toward the heavy body ('111, claim 29)	selecting by repeated experiments or by computer simulation the relative depths of the well and the junction and the doping concentration gradient between the heavy body and the well so that the peak electric field is moved toward the centers of the cells, which are approximately halfway between adjacent trenches
33. epitaxial mesas ('111, claim 29)	the remaining flat-topped portion of the epitaxial layer after trenches have been formed in the epitaxial layer
34. acting as a field plate to extend the device breakdown voltage in the termination region ('947, claims 1, 5, 6)	forming a trenched conductive ring in the termination region, resulting in a higher breakdown voltage in the termination region by modifying the electric field distribution and causing modification of the depletion layer in the substrate
35. isolation trench ('947, claim 1)	a valley filled with dielectric material surrounded by sidewalls in the periphery of a semiconductor substrate that can prevent leakage into the substrate
36. a plurality of elongated inner runners extending in the same direction ('947, claim 6)	multiple substantially parallel gate trenches filled with a conductive material extending in one direction cross the active transistor region
37. single conductor ('947, claim 1)	a first conductor portion electrically coupled to a second conductor portion.
termination region ('947, claim 1)	a peripheral diffusion region with conductivity type the same as the body regions on the die surface that is not part of the active cell array

Exhibit A

AOS's Preliminary Claim Construction Pursuant to L.R. 4-2

I. PRELIMINARY DESIGNATION OF EXTRINSIC EVIDENCE UNDER 4-2(b)

AOS hereby designates the following evidence under Patent Local Rule 4-2(b), without admission that this constitutes "extrinsic evidence" as defined by the Federal Circuit or other relevant legal authority. AOS reserves the right to amend or supplement this list after receiving Fairchild's Patent L.R. 4-2 disclosure and the associated meet and confer communications.

Testimony: AOS anticipates that it may rely upon the testimony of an expert as to the understanding of the claim terms by someone of ordinary skill in the art. AOS may also rely upon the testimony of the inventors, prosecuting attorneys, or corporate representatives.

- 1. Oxford English Dictionary (online): definitions of adjacent, proximal, and several.
- 2. Pages 14, 728, 941, and 1073 of MERRIAM WEBSTER'S COLLEGIATE DICTIONARY (10th ed. 1997) (definitions of adjacent, mesa, proximal, and several).
- 3. Pages 16, 1167, and 1324 of MICROSOFT ENCARTA COLLEGE DICTIONARY (2001) (definitions of adjacent, proximal, and several).
- 4. S. M. Sze, Physics of Semiconductor Devices (1981). FAIR0017267-FAIR0017314.
- 5. http://en.wikipedia.org/wiki/Finite element analysis
- 6. U.S. Patent No. 5,233,215.

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CORP., a Delaware corporation,

Defendant and Counterclaimant.

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AND RELATED COUNTERCLAIMS.

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PROOF OF SERVICE C07-02638 JSW (CONSOLIDATED WITH C-07-02664 JSW)

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Alpha & Omega Semiconductor v. Fairchild Semiconductor USND-C07-02638 JSW (Consolidated with C-07-02664 JSW)

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I am a resident of the State of California and over the age of eighteen years, and not a party to the within action; my business address is 2 Palo Alto Square, 3000 El Camino Real, Suite 700, Palo Alto, CA 94306.

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On January 9, 2008, I served the following document on the parties listed below:

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• AOS'S PRELIMINARY CLAIM CONSTRUCTION PURSUANT TO PATENT LOCAL RULE 4-2

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• EXHIBIT A TO AOS'S PRELIMINARY CLAIM CONSTRUCTION PURSUANT TO PATENT LOCAL RULE 4-2

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Executed on January 9, 2008, at Palo Alto, California.

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I declare under penalty of perjury, under the laws of the State of California, that the above is true and correct.

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David V. Sanker

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